



HPC65R180

**180mΩ, 650V, Super Junction
N-Channel Power MOSFET**

General Description

The HPC65R180 is a high voltage power MOSFET, fabricated using advanced super junction technology. The resulting device has extremely low on resistance, low gate charge and fast switching time, making it especially suitable for applications which require superior power density and outstanding efficiency.

The HPC65R180 break down voltage is 650V and it has a high rugged avalanche characteristics. The HPC65R180 is available in TO-220F, TO-220C, TO-262 and TO-247 packages.

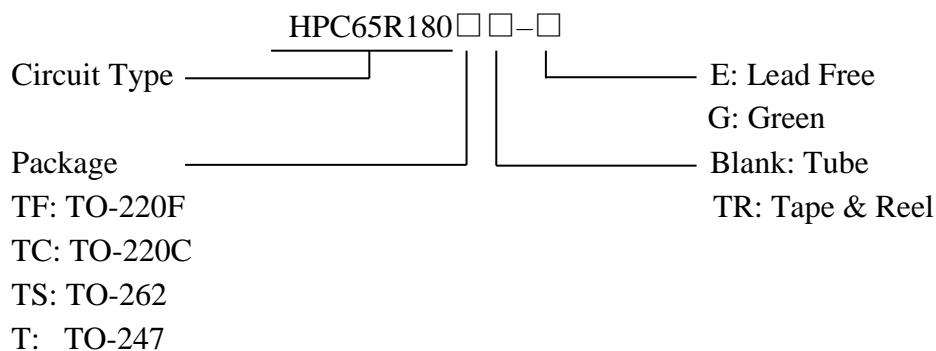
Features

- Ultra Low $R_{DS(ON)} = 180\text{m}\Omega$ @ $V_{GS} = 10\text{V}$.
- Ultra Low Gate Charge, $Q_g = 38\text{nC}$ typ.
- Fast switching capability
- Robust design with better EAS performance
- EMI Improved

Application

- UPS, Inverter, etc
- Solar
- TV Power
- High Power AC/DC Power Supply

Ordering Information



Package	Part Number		Marking ID		Packing Type
	Lead Free	Green	Lead Free	Green	
TO-220F	HPC65R180TF-E	HPC65R180TF-G	HPC65R180TFE	HPC65R180TFG	Tube
TO-220C	HPC65R180TC-E	HPC65R180TC-G	HPC65R180TCE	HPC65R180TCG	Tube
TO-262	HPC65R180TS-E	HPC65R180TS-G	HPC65R180TSE	HPC65R180TSG	Tube

Symbol

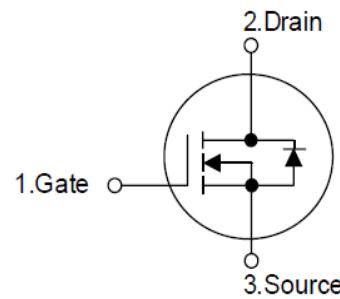


Figure 1 Symbol of HPC65R180

Package Type

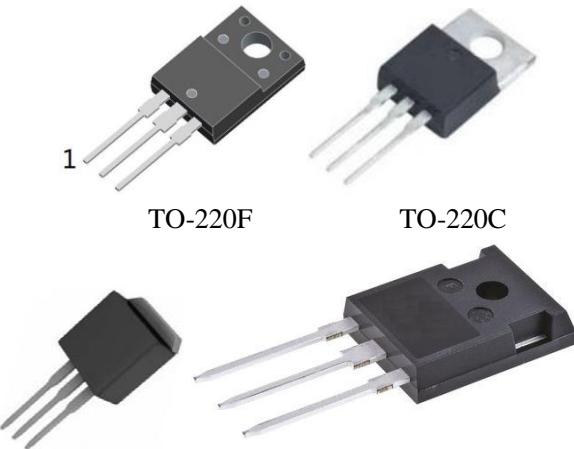


Figure 2 Package Types of HPC65R180



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TO-247	HPC65R180T-E	HPC65R180T-G	HPC65R180TE	HPC65R180TG	Tube
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Absolute Maximum Ratings

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V _{DSS}	650	V
Gate-Source Voltage	V _{GSS}	±30	V
Continuous Drain Current T _C =25°C	I _D	21.2	A
T _C =125°C		9.5	
Pulsed Drain Current (Note 2)	I _{DM}	64	A
Avalanche Energy, Single Pulse (Note 3)	E _{AS}	505	mJ
Avalanche Energy, Repetitive (Note 2)	E _{AR}	0.7	mJ
Avalanche Current, Repetitive (Note 2)	I _{AR}	3.6	A
Continuous Diode Forward Current	I _S	21.2	A
Diode Pulse Current	I _{S.PULSE}	64	A
MOSFET dv/dt Ruggedness, V _{DS} <=480V	dv/dt	50	V/ns
Reverse Diode dv/dt, V _{DS} <=480V, I _{SD} <=I _D	dv/dt	15	V/ns
Operating Junction Temperature	T _J	150	°C
Storage Temperature	T _{STG}	-55 to 150	°C
Lead Temperature (Soldering, 10 sec)	T _{LEAD}	260	°C

Note:

1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.
Absolute maximum ratings are stress ratings only and functional device operation is not implied.
2. Repetitive Rating: Pulse width limited by maximum junction temperature
3. I_{AS} = 3.6A, V_{DD} = 60V, R_G = 25Ω, Starting T_J = 25°C



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Electrical Characteristics

$T_J = 25^\circ\text{C}$, unless otherwise specified.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$	650			V
Zero Gate Voltage Drain Current	I_{DSS}	$\text{V}_{\text{DS}}=650\text{V}, \text{V}_{\text{GS}}=0\text{V}$			1	μA
Gate-Body Leakage Current	Forward	I_{GSSF}	$\text{V}_{\text{GS}}=30\text{V}, \text{V}_{\text{DS}}=0\text{V}$		100	nA
	Reverse	I_{GSSR}	$\text{V}_{\text{GS}}=-30\text{V}, \text{V}_{\text{DS}}=0\text{V}$		-1.0	μA
Gate Threshold Voltage	$\text{V}_{\text{GS}(\text{TH})}$	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_D=250\mu\text{A}$	2.4	3.4	4.4	V
Static Drain-Source On-Resistance	$\text{R}_{\text{DS}(\text{ON})}$	$\text{V}_{\text{GS}}=10\text{V}, \text{I}_D=10.0\text{A}$		160	180	$\text{m}\Omega$
Gate Resistance	R_G	f=1MHz, Open Drain		1.7		Ω

Dynamic Characteristics

Input Capacitance	C_{ISS}	$\text{V}_{\text{DS}}=50\text{V}, \text{V}_{\text{GS}}=0\text{V}, \text{f}=1\text{MHz}$		1630		pF
Output Capacitance	C_{OSS}			110		
Reverse Transfer Capacitance	C_{RSS}			22		
Effective output capacitance, energy related ^{NOTE5}	$\text{C}_{\text{O(er)}}$	$\text{V}_{\text{GS}}=0\text{V}, \text{V}_{\text{DS}}=0\ldots 480\text{V}$		71		pF
Effective output capacitance, time related ^{NOTE6}	$\text{C}_{\text{O(tr)}}$			301		
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$\text{V}_{\text{DD}}=400\text{V}, \text{I}_D=10.0\text{A}$ $\text{R}_G=3.4\Omega, \text{V}_{\text{GS}}=10\text{V}$		11		ns
Rise Time	t_r			10		
Turn-off Delay Time	$t_{\text{d}(\text{off})}$			76		
Fall Time	t_f			8		

Gate Charge Characteristics

Gate to Source Charge	Q_{gs}	$\text{V}_{\text{DD}}=480\text{V}, \text{I}_D=10.0\text{A}$ $\text{V}_{\text{GS}}=0 \text{ to } 10\text{V}$		10.6		nC
Gate to Drain Charge	Q_{gd}			12.2		
Gate Charge Total	Q_g			38		
Gate Plateau Voltage	$\text{V}_{\text{plateau}}$			5.5		

Reverse Diode Characteristics

Drain-Source Diode Forward Voltage	V_{SD}	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_{\text{SD}}=10.0\text{A}$		0.83	1.1	V
Reverse Recovery Time	t_{rr}	$\text{V}_{\text{R}}=400\text{V}, \text{I}_{\text{F}}=10.0\text{A}$ $d\text{I}_{\text{F}}/dt=100.0\text{A}/\mu\text{s}$		330		ns
Reverse Recovery Charge	Q_{rr}			4.5		uC
Peak Reverse Recovery Current	I_{rrm}			27		A

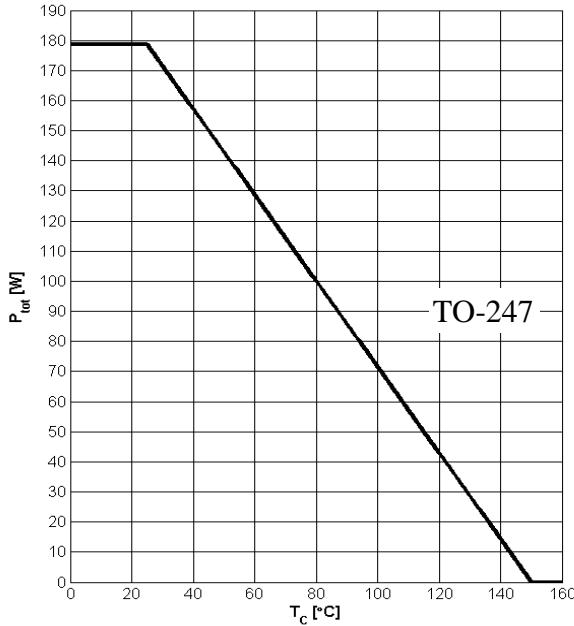
Note:

5. $\text{C}_{\text{O(er)}}$ is a fixed capacitance that gives the same stored energy as C_{OSS} while V_{DS} is rising from 0 to 480V

6. $\text{C}_{\text{O(tr)}}$ is a fixed capacitance that gives the same charging time as C_{OSS} while V_{DS} is rising from 0 to 480 V

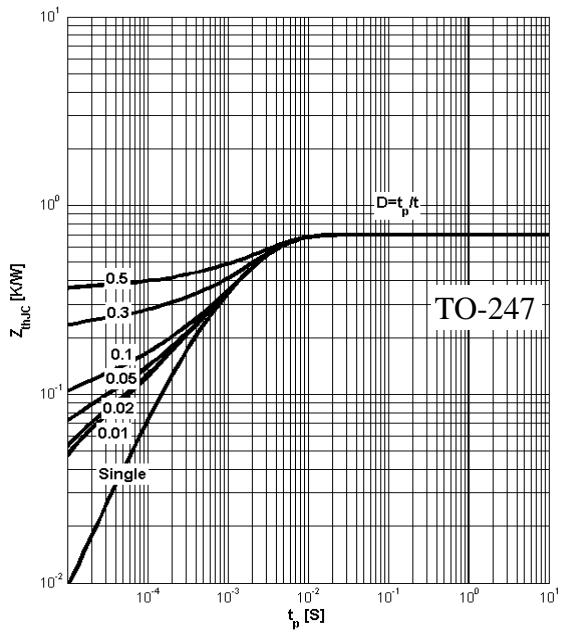
Typical Performance Characteristics

Figure 3: Power Dissipation



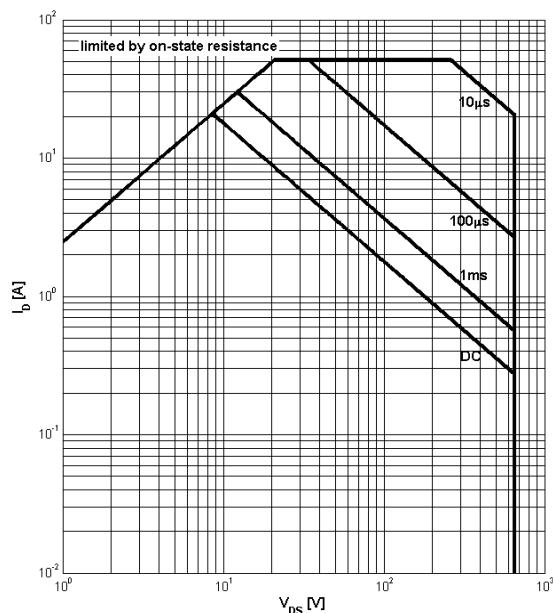
$$P_{tot} = f(T_c)$$

Figure 4: Max. Transient Thermal Impedance



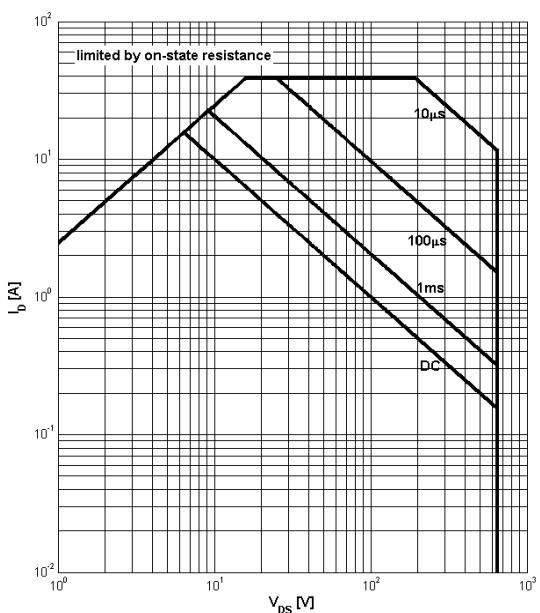
$$Z_{thJC} = f(t_p); \text{ parameter: } D = t_p/T$$

Figure 5: Safe Operating Area



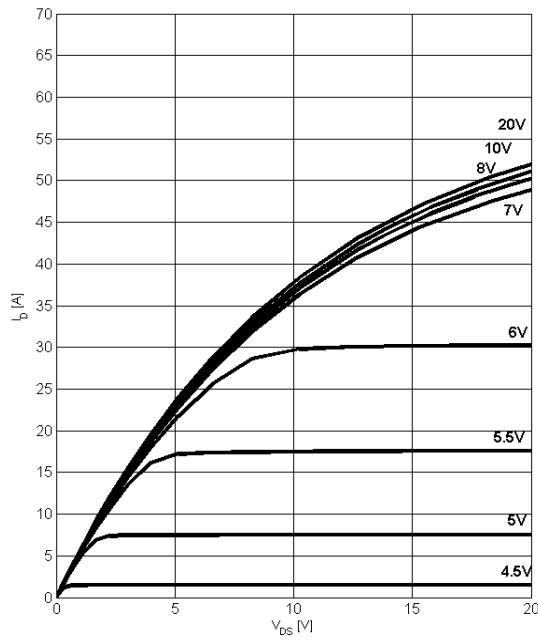
$$I_D = f(V_{DS}); T_c = 25^\circ\text{C}; V_{GS} > 7\text{V}; \text{ parameter } t_p$$

Figure 6: Safe Operating Area



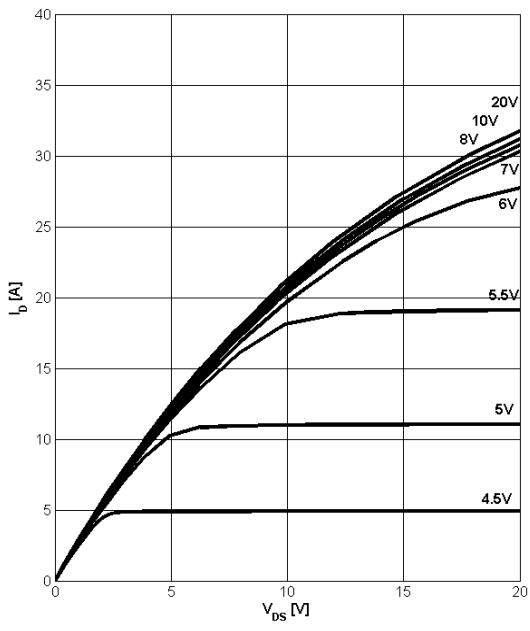
$$I_D = f(V_{DS}); T_c = 80^\circ\text{C}; V_{GS} > 7\text{V}; \text{ parameter } t_p$$

Figure 7: Typ. Output Characteristics



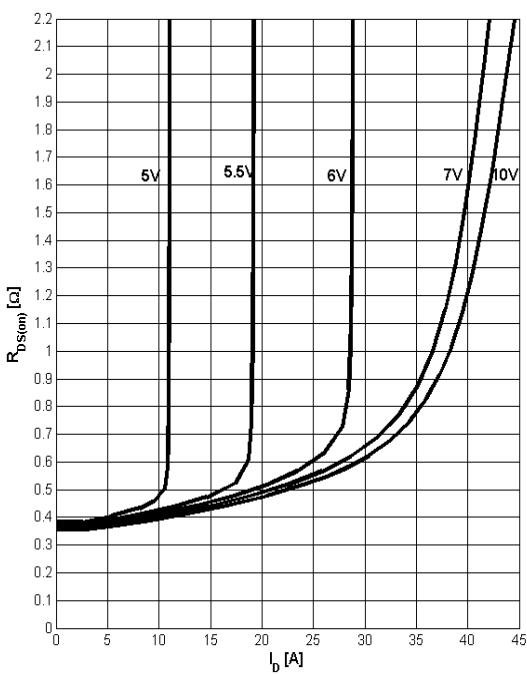
$I_D = f(V_{DS})$; $T_j = 25^\circ\text{C}$; parameter: V_{GS}

Figure 8: Typ. Output Characteristics



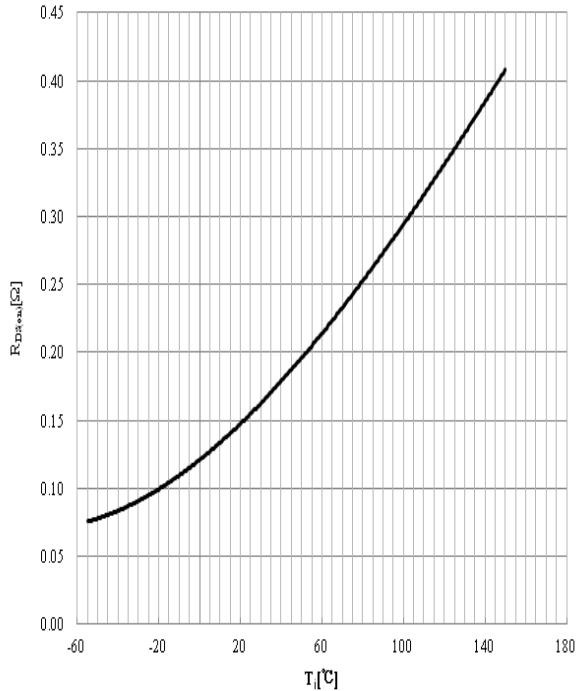
$I_D = f(V_{DS})$; $T_j = 125^\circ\text{C}$; parameter: V_{GS}

Figure 9: Typ. Drain-Source On-State Resistance



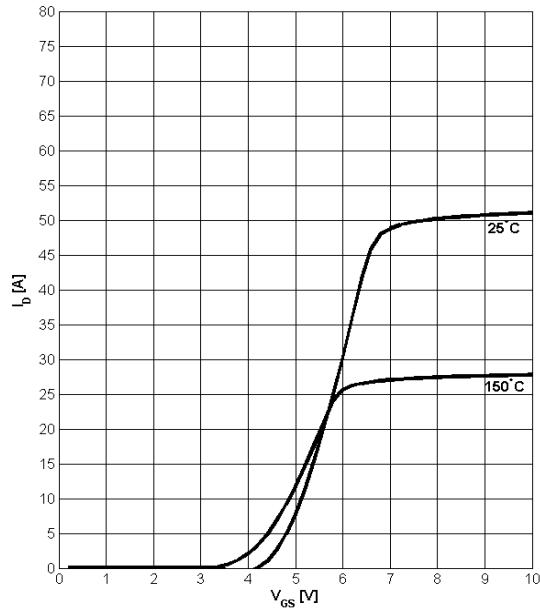
$R_{DS(ON)} = f(I_D)$; $T_j = 125^\circ\text{C}$; parameter: V_{GS}

Figure 10: Typ. Drain-Source On-State Resistance



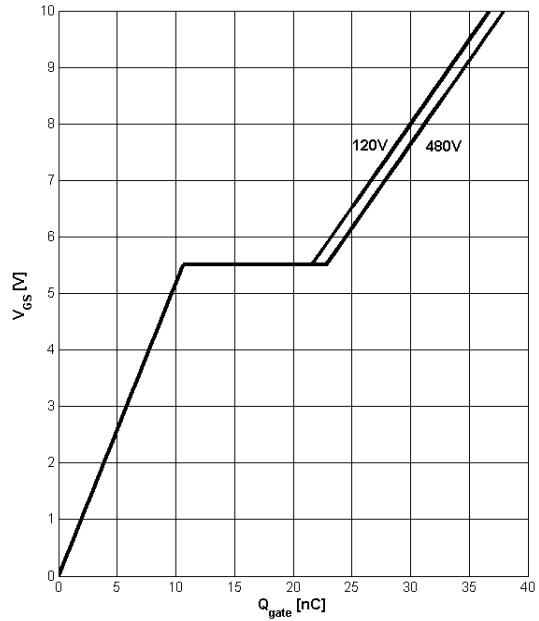
$R_{DS(ON)} = f(T_j)$; $I_D = 10\text{A}$; $V_{GS} = 10\text{V}$

Figure 11: Typ. Transfer Characteristics



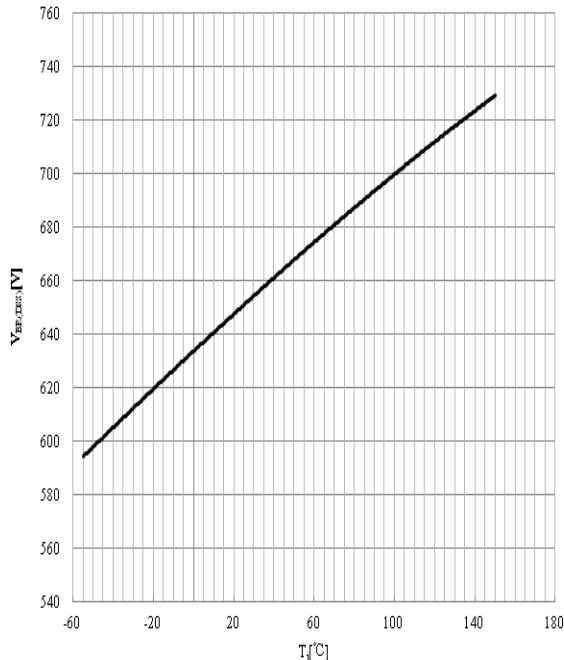
$I_D = f(V_{GS})$; $V_{DS} = 20V$

Figure 12: Typ. Gate Charge



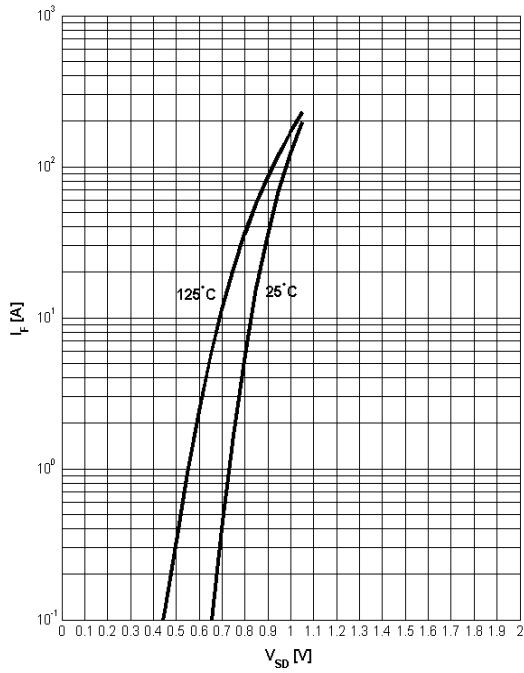
$V_{GS} = f(Q_{gate})$, $I_D = 10A$ pulsed

Figure 13: Drain-Source Breakdown Voltage



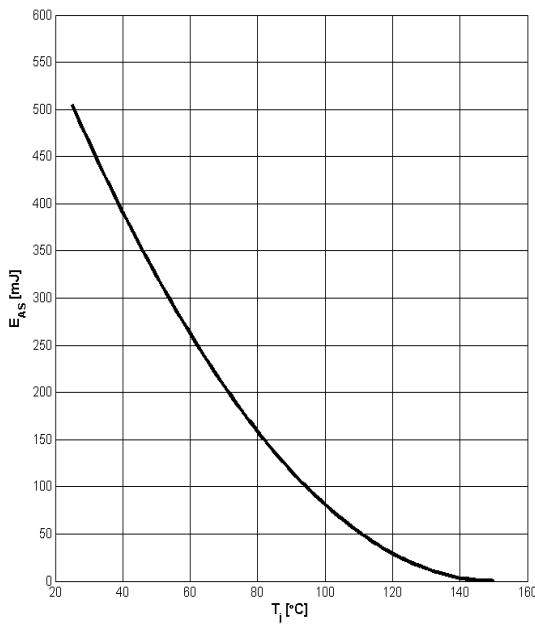
$V_{BR(DSS)} = f(T_j)$; $I_D = 1mA$

Figure 14: Forward Characteristics of Reverse Diode



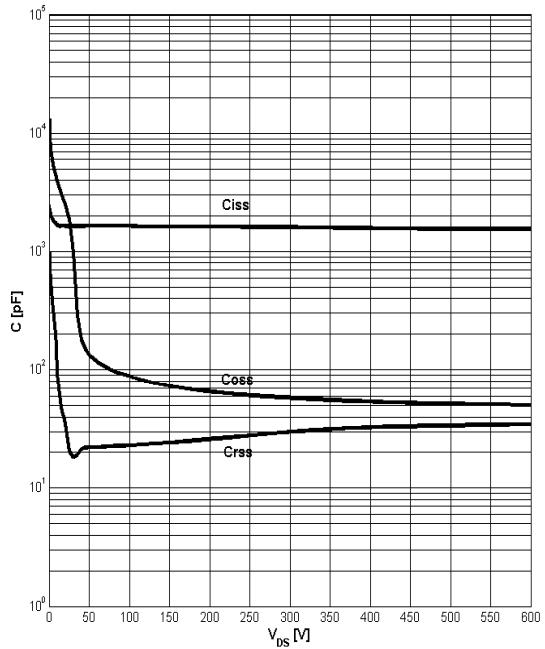
$I_F = f(V_{SD})$; parameter: T_j

Figure 15: Avalanche Energy



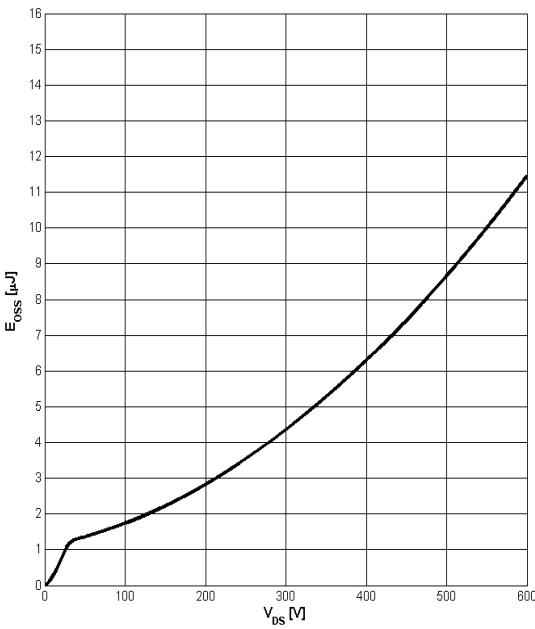
$$E_{AS}=f(T_j); I_D=3.6A; V_{DD}=60V$$

Figure 16: Typ. Capacitances



$$C=f(V_{DS}); V_{GS}=0; f=1MHz$$

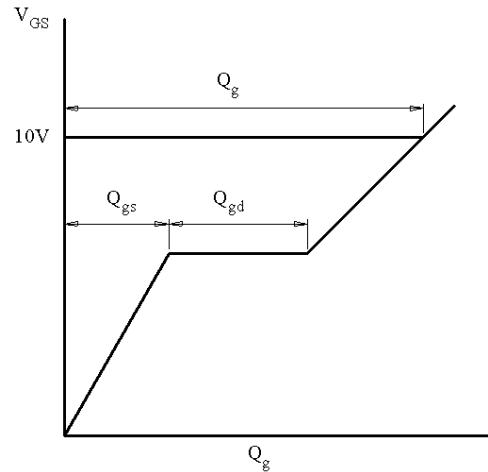
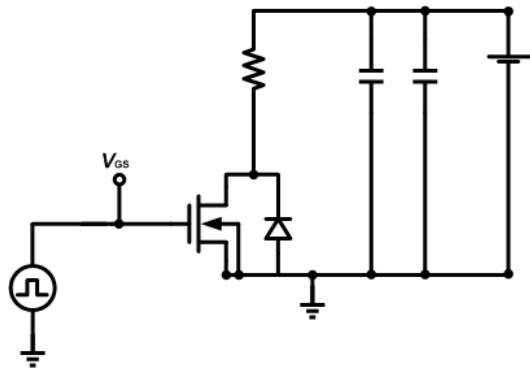
Figure 17: Coss Stored Energy



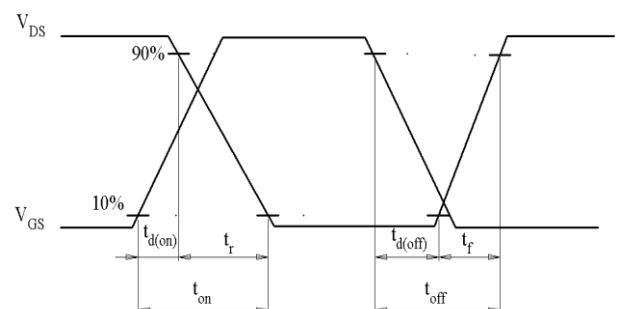
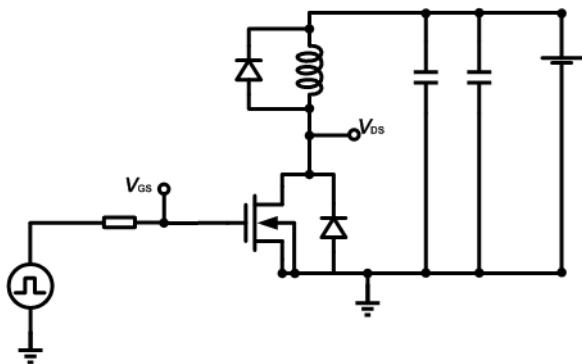
$$E_{oss}=f(V_{DS})$$

Test Circuits

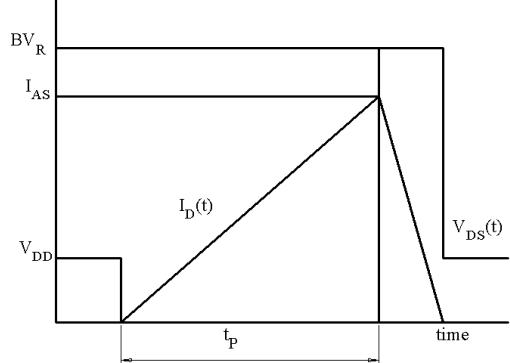
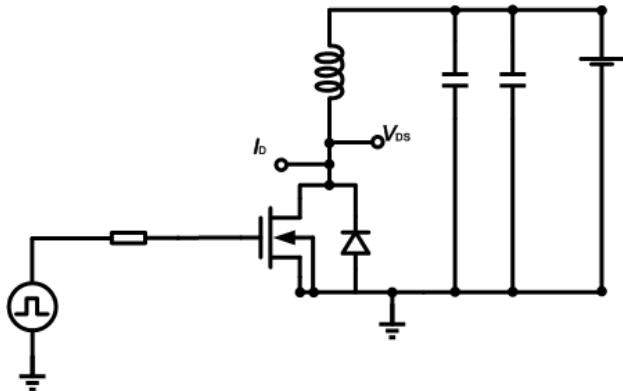
1. Gate Charge Test Circuit & Waveform



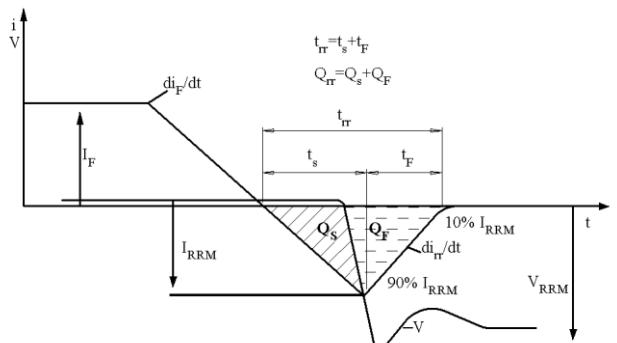
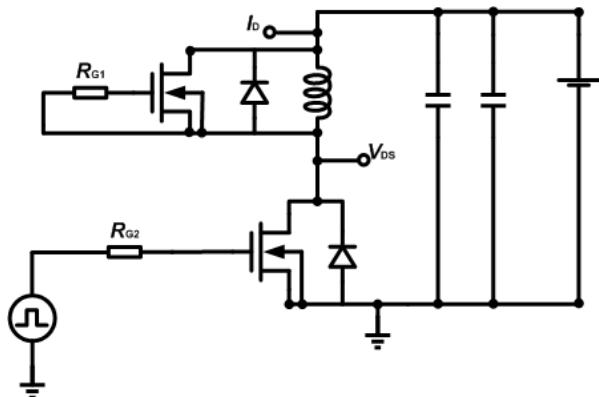
2. Switch Time Test Circuit



3. Unclaimed Inductive Switching Test Circuit & Waveforms



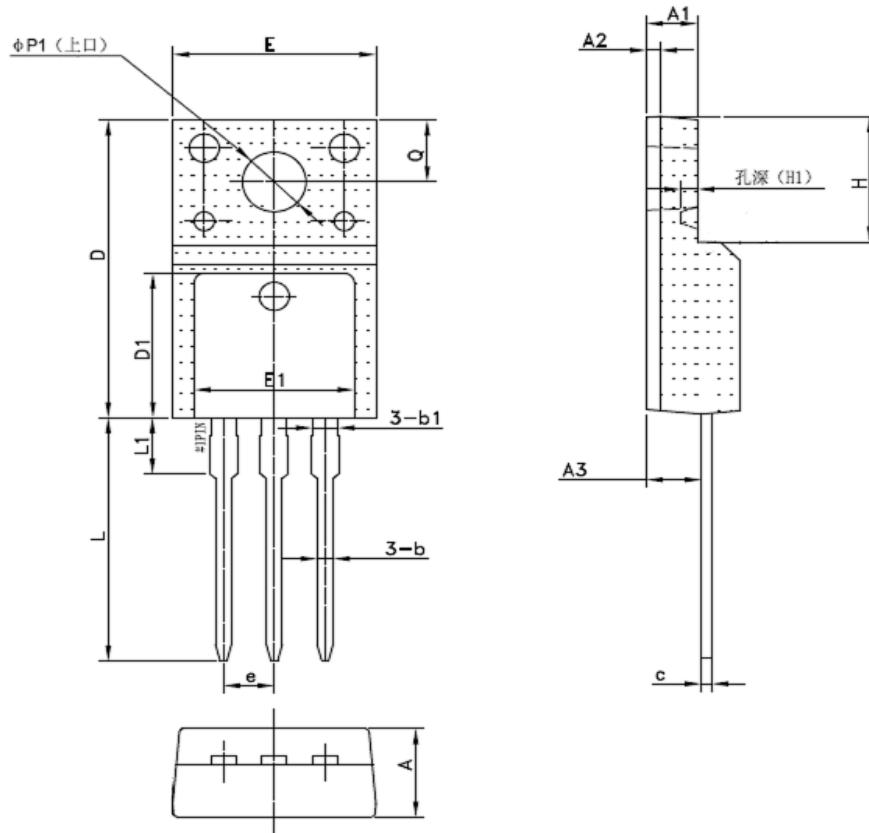
4. Test Circuit and Waveform for Diode Characteristics



Mechanical Dimensions

TO-220F

Unit: mm

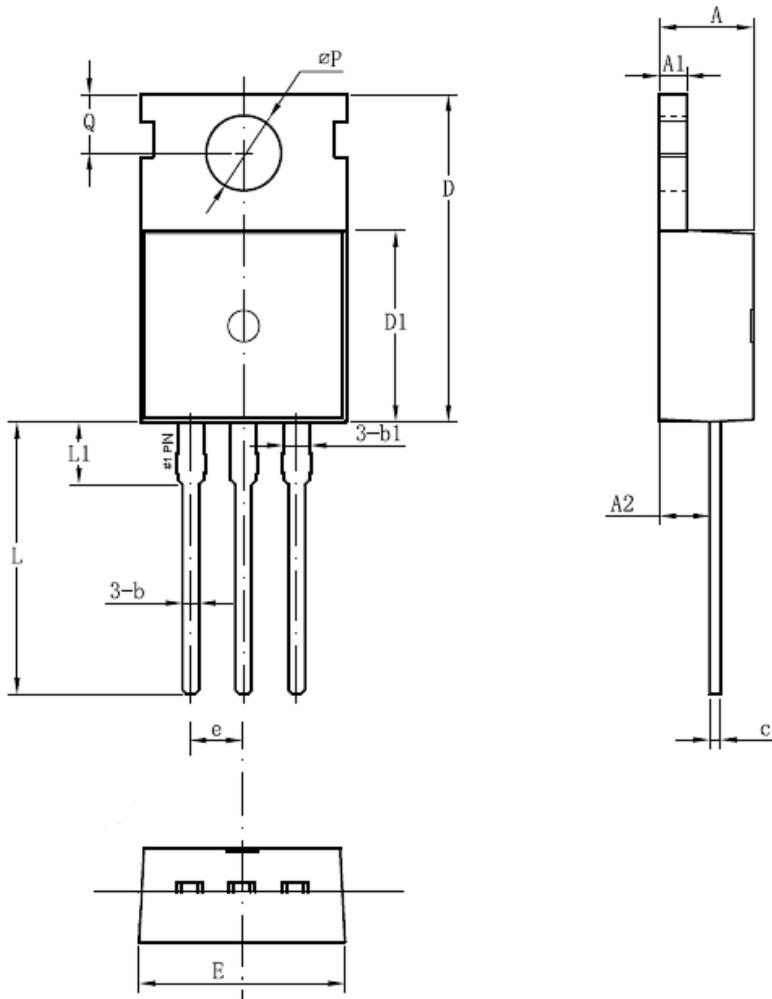


Symbol	Dimensions(mm)		
	Min.	Typ.	Max.
A	4.30	4.70	4.90
A1	2.34	2.54	2.90
A2	-	0.70	-
A3	2.56	2.76	2.96
b	0.55	-	0.95
b1	-	1.28	-
c	0.42	0.50	0.70
D	14.70	-	16.07
D1	-	7.70	-
E	9.96	10.16	10.36
E1	-	8.00	-
e	2.54(BSC)		
H	-	6.70	-
(H1)	-	(0.81)	-
L	12.48	12.98	13.50
L1	-	2.93	-
ΦP1	-	3.18	-
Q	2.90	3.30	3.50

Mechanical Dimensions (Continued)

TO-220C

Unit: mm

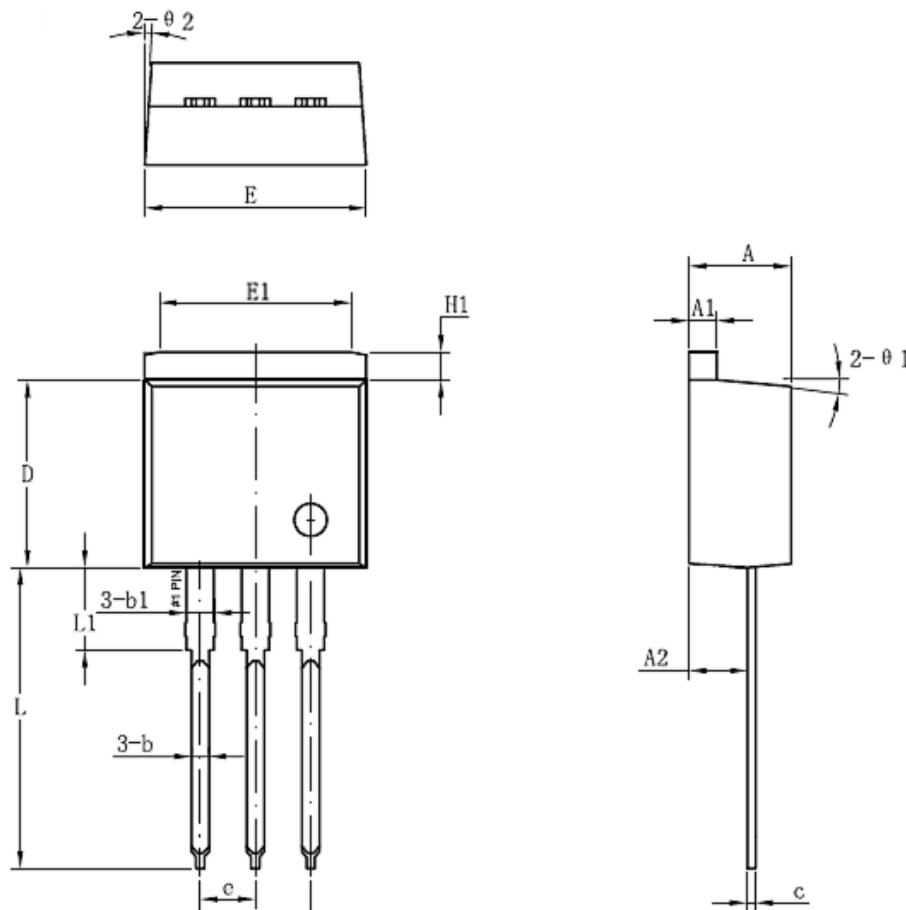


Symbol	Dimensions(mm)		
	Min.	Typ.	Max.
A	4.30	4.50	4.70
A1	1.20	1.30	1.40
A2	2.20	2.40	2.60
b	0.70	0.80	0.95
b1	-	1.27	-
c	0.40	0.50	0.65
D	15.20	15.70	16.20
D1	9.00	9.20	9.40
E	9.70	10.00	10.20
e	2.54(BSC)		
L	12.60	13.08	13.60
L1	-	3.00	-
ΦP	3.50	3.60	3.80
Q	2.60	2.80	3.00

Mechanical Dimensions (Continued)

TO-262

Unit: mm



Symbol	Dimensions(mm)		
	Min.	Typ.	Max.
A	4.30	4.65	4.85
A1	1.17	1.27	1.40
A2	2.20	-	2.89
b	0.70	0.81	0.96
b1	-	1.27	-
c	0.36	0.40	0.61
D	8.55	-	9.4
E	9.80	10.10	10.31
E1	-	8.80	-
e	2.54(BSC)		
H1	1.00	1.25	1.40
L	12.60	-	14.08
L1	-	3.8	-
θ1	5°		
θ2	4°		



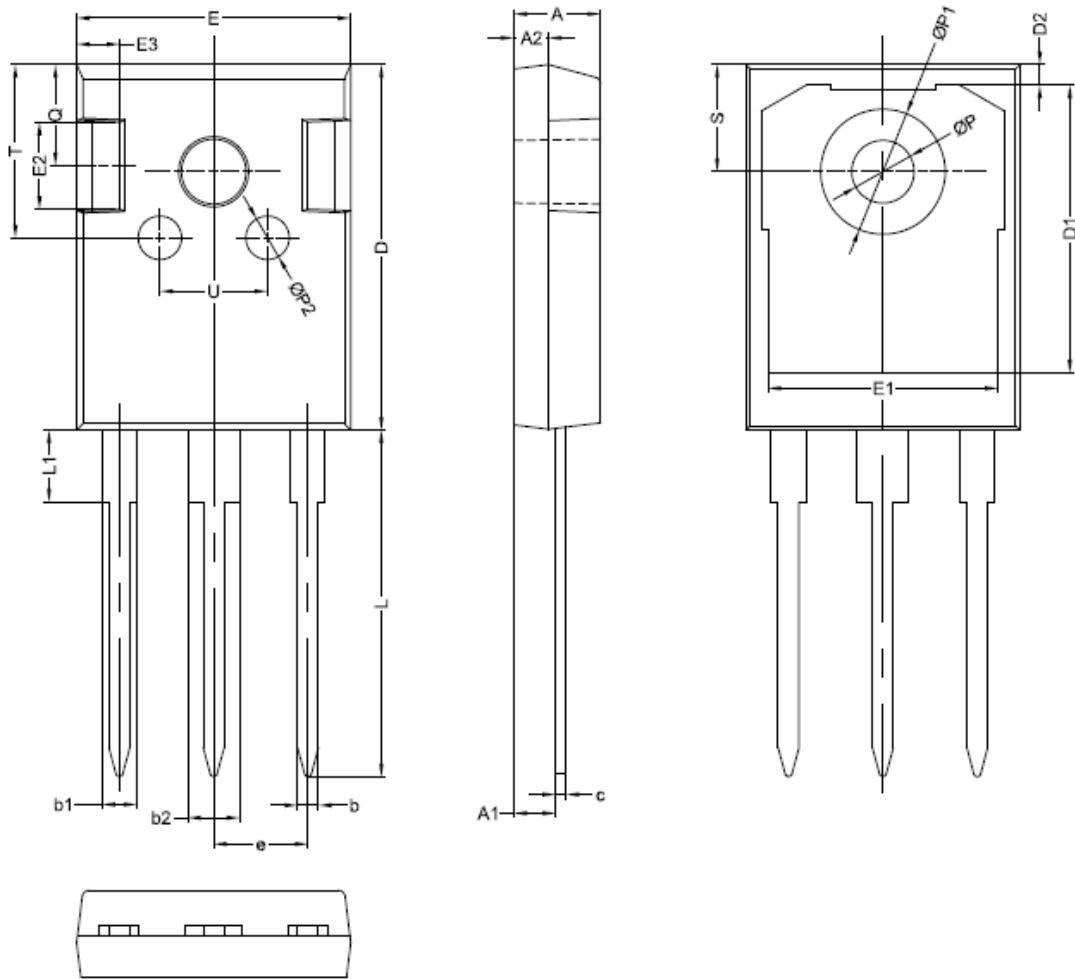
HPC65R180

**180mΩ, 650V, Super Junction
N-Channel Power MOSFET**

Mechanical Dimensions (Continued)

TO-247

Unit: mm



Symbol	Dimensions(mm)			Symbol	Dimensions(mm)		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.80	5.00	5.20	E2	-	5.00	-
A1	2.21	2.41	2.61	E3	-	2.50	-
A2	1.90	2.00	2.10	e	5.44(BSC)		
b	1.10	1.20	1.35	L	19.42	19.92	20.42
b1	-	2.00	-	L1	-	4.13	-
b2	-	3.00	-	P	3.50	3.60	3.70
c	0.55	0.60	0.75	P1	-	-	7.40
D	20.80	21.00	21.20	P2	-	2.50	-
D1	-	16.55	-	Q	-	5.80	-
D2	-	1.20	-	S	6.05	6.15	6.25
E	15.60	15.80	16.00	T	-	10.00	-
E1	-	13.30	-	U	-	6.20	-



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